

# NIE PCB Fabrication Facility Production Parameters

## PRODUCTION PARAMETERS

S.No	Parameter	Value
<b>General</b>		
1	Substrate (Customer provided material also acceptable)	FR-4
2	Type of PCB	Rigid
3	Max. number of layers	6
4	PCB size - Single and Double Layer	11" x 14"
5	PCB Size - Multilayer	11.5" x 8"
6	PCB Thickness	1mm, 1.6mm, 2mm
<b>Production</b>		
7	Track to track outer layer clearance	
8	Track to Track Inner layer clearance	
9	Track to Pad clearance outer Layer	
10	Track to Pad clearance inner Layer	
11	Pad to Pad clearance	8 mil
12	Minimum Track Width Outer Layer	
13	Minimum Track Width Inner Layer	
14	Minimum Annular Ring	
15	Minimum Board Edge to Conductor	3 mm
<b>Drilling/Routing</b>		
16	Minimum Hole/Drill Size	0.4 mm
17	Maximum Hole/Drill Size	3.5 mm
18	Minimum Two Drill Hole Distance	10 mil
19	Drill Hole to Inner Layer Track clearance	16 mil
20	Minimum PTH Slot width	1 mm
<b>Surface Finish</b>		
21	Surface Finish	Tin
22	Solder Mask Clearance	8 mil
23	Minimum Solder Mask ring	6 mil
24	Legend Component Designator & Writing Clearance from SMT Pads	10 mil
25	Legend Character Height	1 mm